

ABSTRACT

A method of manufacturing single-crystal semiconductor wafers is characterized in that a plurality of single-crystal semiconductor wafers of a relatively small diameter (2a-2d) desired by users are cut out from a single-crystal semiconductor wafer of a 5 relatively large diameter (1a-1d). Therefore, there can also be obtained a secondary effect that even if the large-scale single-crystal semiconductor wafer has defective parts, the small-scale wafers cut out from the non-defective parts can be shipped to the market.